

All ratings @ $T_j = 25^\circ\text{C}$ unless otherwise specified

Electrical Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
V_F	Diode Forward Voltage	$I_F = 75\text{A}$	$T_j = 25^\circ\text{C}$		1.6	V
			$T_j = 125^\circ\text{C}$		1.6	
I_{RM}	Maximum Reverse Leakage Current	$V_R = 1200\text{V}$	$T_j = 25^\circ\text{C}$		250	μA
			$T_j = 125^\circ\text{C}$		500	

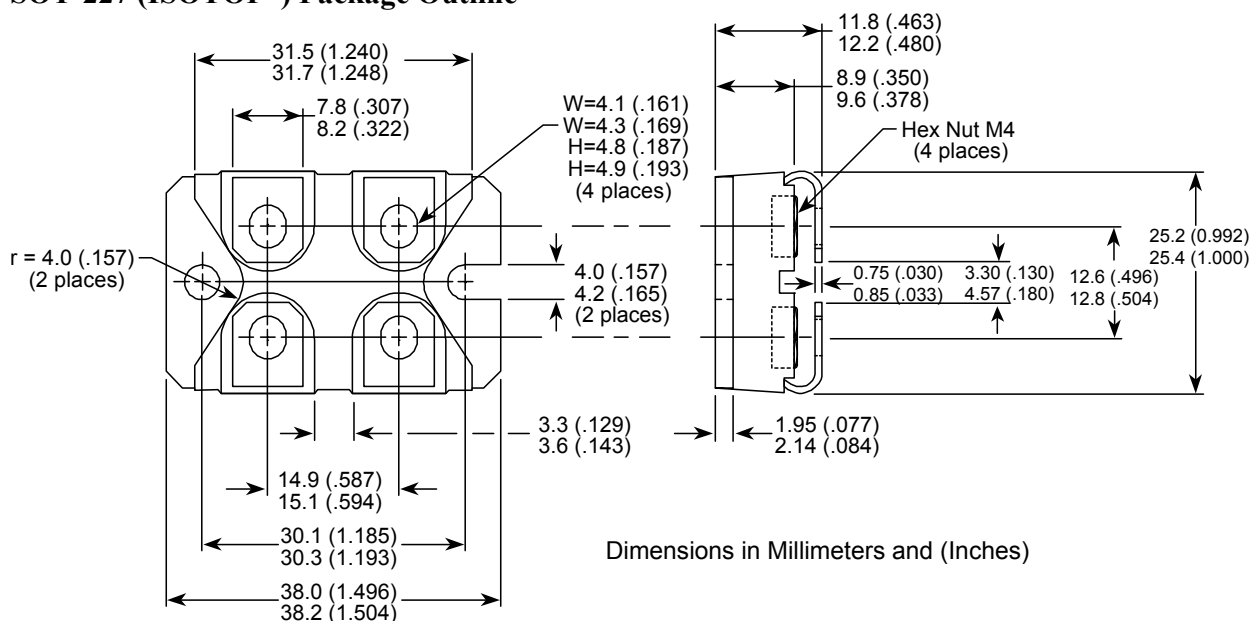
Dynamic Characteristics

Symbol		Characteristic	Test Conditions		Min	Typ	Max	Unit
t _{rr}	Reverse Recovery Time	I _F = 75A V _R = 600V di/dt = 2000A/μs	T _j = 25°C			170		ns
			T _j = 125°C			280		
Q _{rr}	Reverse Recovery Charge		T _j = 25°C			7		μC
			T _j = 125°C			14		
E _{rr}	Reverse Recovery Energy		T _j = 25°C			3		mJ
			T _j = 125°C			5.5		

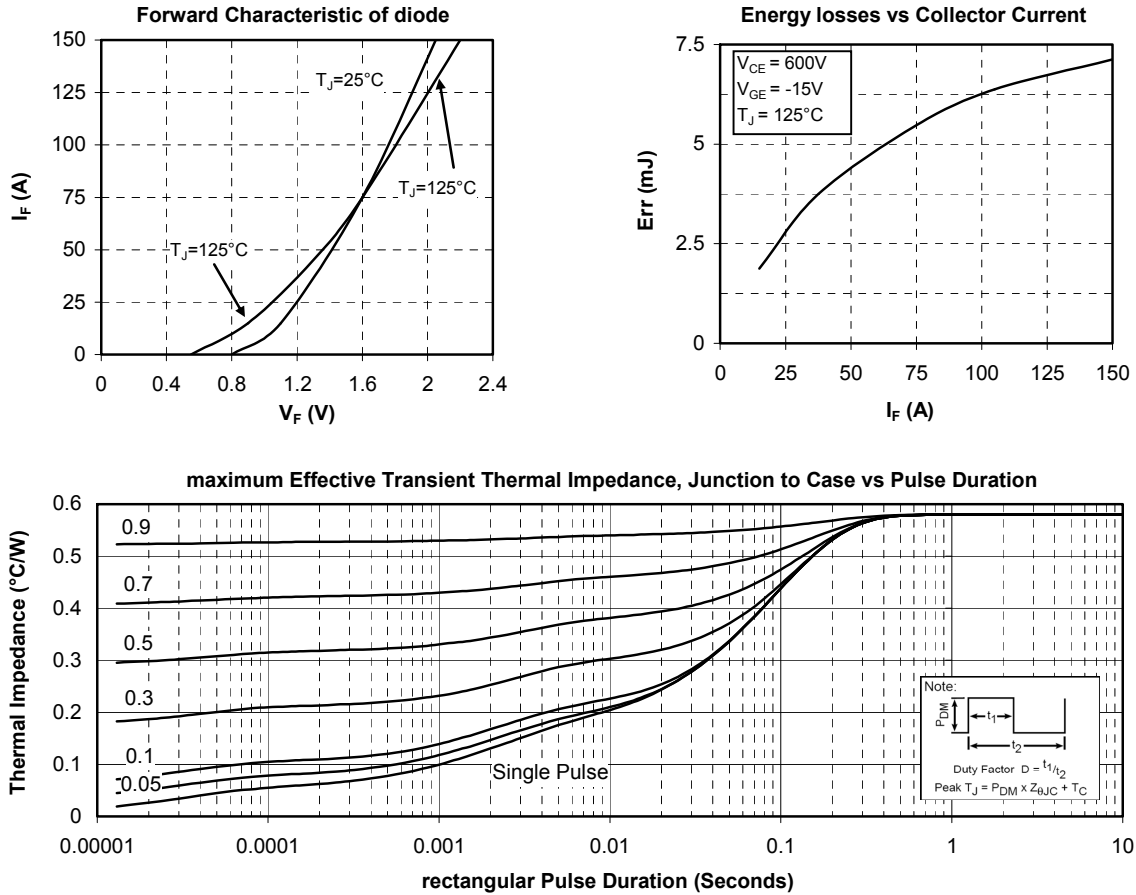
Thermal and package characteristics

Symbol	Characteristic	Min	Typ	Max	Unit
R_{thJC}	Junction to Case Thermal resistance			0.58	$^\circ\text{C}/\text{W}$
R_{thJA}	Junction to Ambient			20	
V_{ISOL}	RMS Isolation Voltage, any terminal to case $t = 1\text{ min}$, 50/60Hz	2500			V
T_j, T_{STG}	Storage Temperature Range	-55		150	$^\circ\text{C}$
T_L	Max Lead Temp for Soldering: 0.063" from case for 10 sec			300	
Torque	Mounting torque (Mounting = 8-32 or 4mm Machine and terminals = 4mm Machine)			1.5	N.m
Wt	Package Weight		29.2		g

SOT-227 (ISOTOP[®]) Package Outline



Typical Performance Curve



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